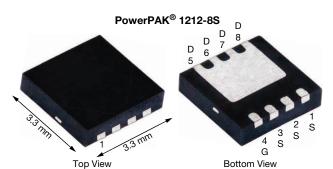
Vishay Siliconix

N-Channel 70 V (D-S) MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	70				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5 \text{ V}$	0.00625				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 3.3 \text{ V}$	0.0069				
Q _g typ. (nC)	16.5				
I _D (A)	67.4				
Configuration	Single				

FEATURES

- TrenchFET® Gen IV power MOSFET
- Very low R_{DS} x Q_g figure-of-merit (FOM)
- Tuned for the lowest R_{DS} x Q_{oss} FOM

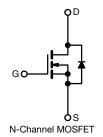
• 100 % R_a and UIS tested

 Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

RoHS COMPLIANT HALOGEN FREE

APPLICATIONS

- DC/DC conversion topologies
- Bus converters
- Synchronous rectification
- · Primary side switch



ORDERING INFORMATION	
Package	PowerPAK 1212-8S
Lead (Pb)-free and halogen-free	SiSS76LDN-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	70		
Gate-source voltage		V _{GS}	± 12	V	
	T _C = 25 °C		67.4		
Continuous drain current (T _J = 150 °C)	T _C = 70 °C	1 , 🗔	54		
	T _A = 25 °C	I _D	19.6 ^{b, c}		
	T _A = 70 °C		15.6 ^{b, c}	Α	
Pulsed drain current (t = 100 µs)		I _{DM}	120		
One first and the second second	T _C = 25 °C		51.8		
Continuous source-drain diode current	T _A = 25 °C	I _S	4.3 ^{b, c}		
Single pulse avalanche current		I _{AS}	20		
Single pulse avalanche energy L = 0.1 mH		E _{AS}	20	mJ	
	T _C = 25 °C		57		
Man Control of the Control	T _C = 70 °C		36	W	
Maximum power dissipation	T _A = 25 °C	P _D	4.8 b, c		
	T _A = 70 °C		3 b, c		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) ^c			260		

THERMAL RESISTANCE RATING	as				
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^b	t ≤ 10 s	R _{thJA}	21	26	°C/W
Maximum junction-to-case (drain)	Steady state	R _{thJC}	1.7	2.2	C/VV

Notes

- a. Package limited
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 10 s
- d. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK 1212-8S is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- f. Maximum under steady state conditions is 70 °C/W
- g. T_C = 25 °C



Vishay Siliconix

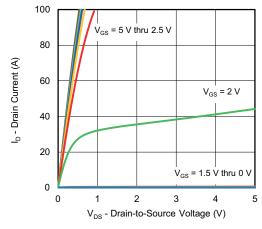
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						l
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	70	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	$\Delta V_{DS}/T_{J}$ $I_{D} = 10 \text{ mA}$		43	-	14/00
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-3.5	-	mV/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.4	-	1.6	V
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$	-	-	100	nA
-		$V_{DS} = 70 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	μΑ
Zero gate voltage drain current	I _{DSS}	V _{DS} = 70 V, V _{GS} = 0 V, T _J = 70 °C	-	-	15	
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	40	-	-	Α
	B(OH)	V _{GS} = 4.5 V, I _D = 10 A	_	0.0052	0.00625	Ω
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = 3.3 V, I _D = 10 A	_	0.0057	0.0069	
Forward transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 10 A	_	21	-	S
Dynamic ^b	315	50 - 7 5				
Input capacitance	C _{iss}		-	2780	_	
Output capacitance	C _{oss}	$V_{DS} = 35 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	260	-	pF
Reverse transfer capacitance	C _{rss}		-	14	-	
otal gate charge	Q _g	$V_{DS} = 35 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$	-	22.3	33.5	nC
			-	16.5	25	
Gate-source charge	Q _{gs}	$V_{DS} = 35 \text{ V}, V_{GS} = 3.3 \text{ V}, I_{D} = 10 \text{ A}$	-	5.4	-	
Gate-drain charge	Q _{gd}		-	4.2	-	
Output charge	Q _{oss}	V _{DS} = 35 V, V _{GS} = 0 V	-	26.2	-	
Gate resistance	R_g	f = 1 MHz	0.3	0.8	1.5	Ω
Turn-on delay time	t _{d(on)}		-	15	30	
Rise time	t _r	V_{DD} = 35 V, R_L = 3.5 Ω , I_D \cong 10 A,	-	8	16	
Turn-off delay time	t _{d(off)}	$V_{GEN} = 6 \text{ V}, R_g = 1 \Omega$	-	32	64]
Fall time	t _f		-	7	14	ne
Turn-on delay time	t _{d(on)}		-	19	38	- ns - -
Rise time	t _r	V_{DD} = 35 V, R_L = 3.5 $\Omega,~I_D \cong 10$ A,	-	40	80	
Turn-off delay time	t _{d(off)}	$V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	-	40	80	
Fall time	t _f		-	12	24	
Drain-Source Body Diode Characteristi	cs					
Continuous source-drain diode current	Is	T _C = 25 °C	-	-	51.8	- A
Pulse diode forward current	I _{SM}		-	-	120	
Body diode voltage	V_{SD}	$I_S = 5 A$, $V_{GS} = 0 V$	-	0.74	1.1	V
Body diode reverse recovery time	t _{rr}		-	29	58	ns
Body diode reverse recovery charge	Q _{rr}	$I_F = 10 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s},$	-	21	42	nC
Reverse recovery fall time	t _a	$T_J = 25 ^{\circ}C$	-	14	-	ns
Reverse recovery rise time	t _b		-	15	-	"13

Notes

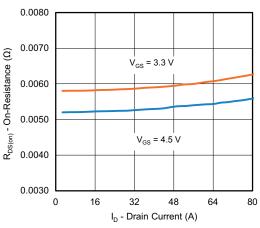
- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

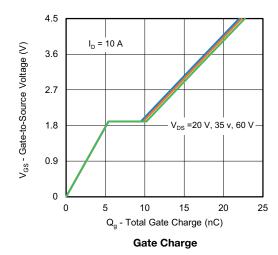


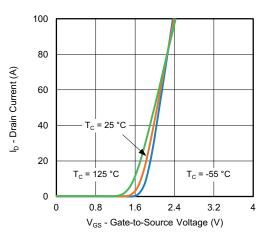


Output Characteristics

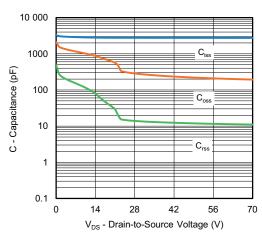


On-Resistance vs. Drain Current and Gate Voltage

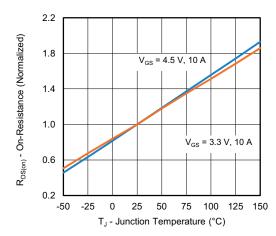




Transfer Characteristics

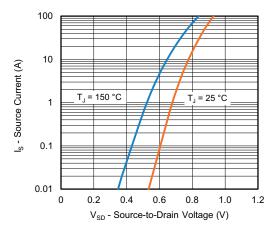


Capacitance

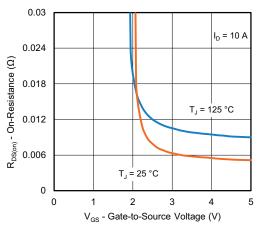


On-Resistance vs. Junction Temperature

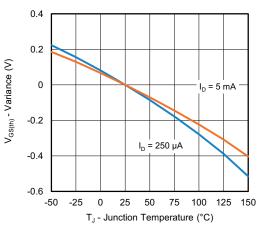




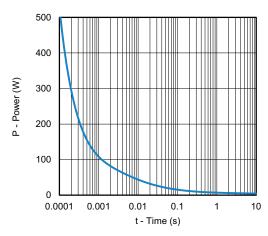
Source-Drain Diode Forward Voltage



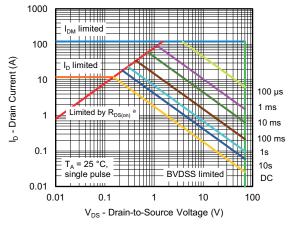
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

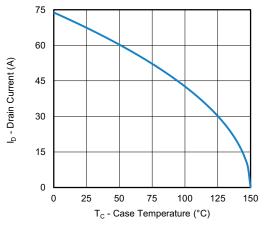


Safe Operating Area, Junction-to-Ambient

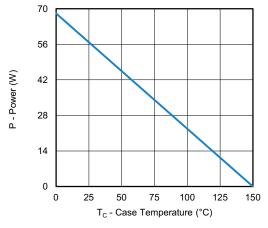
Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

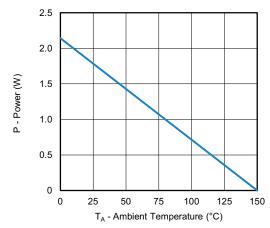




Current Derating a



Power, Junction-to-Case

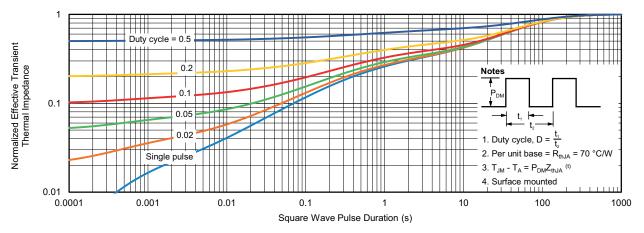


Power, Junction-to-Ambient

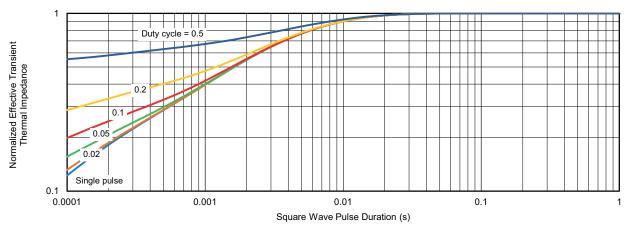
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient

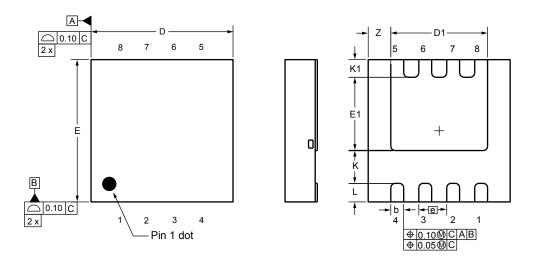


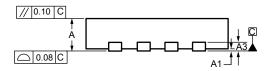
Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?77631.



Case Outline for PowerPAK® 1212-8S





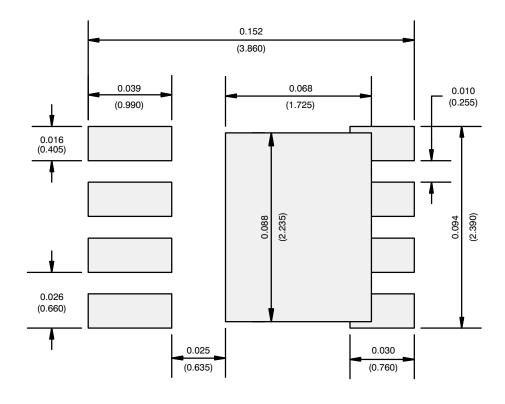
DIM.		MILLIMETERS		INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	0.67	0.75	0.83	0.026	0.030	0.033	
A1	0.00	-	0.05	0.000	-	0.002	
A3		0.20 ref.			0.008 ref		
b	0.25	0.30	0.35	0.010	0.012	0.014	
D	3.20	3.30	3.40	0.126	0.130	0.134	
D1	2.15	2.25	2.35	0.085	0.089	0.093	
E	3.20	3.30	3.40	0.126	0.130	0.134	
E1	1.60	1.70	1.80	0.063	0.067	0.071	
е		0.65 bsc.			0.026 bsc.		
K		0.76 ref.			0.030 ref.		
K1	0.41 ref.			0.016 ref.			
L	0.33	0.43	0.53	0.013	0.017	0.021	
Z	0.525 ref.			0.021 ref.			

ECN: C20-0862-Rev. B, 20-Jul-2020

DWG: 6008



RECOMMENDED MINIMUM PADS FOR PowerPAK® 1212-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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